

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3114423

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the PROVISIONAL APPLICATION 61/598,187 FILED FEBRUARY 13, 2011 previously recorded on Reel 030591 Frame 0001. Assignor(s) hereby confirms the FILING DATE OF PROVISIONAL APPLICATION 61/598,187 FILED FEBRUARY 13, 2012 (NOT 2011).
CONVEYING PARTY DATA	
Name	Execution Date
EUGENE J. BAIK	01/23/2013
SAMEER VERMANI	03/06/2013
LIN YANG	01/23/2013
HEMANTH SAMPATH	04/09/2013
RECEIVING PARTY DATA	
Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department/Central Administration
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13690481
CORRESPONDENCE DATA	
Fax Number:	(858)658-2502
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	858-845-4265
Email:	us-docketing@qualcomm.com
Correspondent Name:	QUALCOMM INCORPORATED
Address Line 1:	5775 MOREHOUSE DR.
Address Line 4:	SAN DIEGO, CALIFORNIA 92121
ATTORNEY DOCKET NUMBER:	120674U1
NAME OF SUBMITTER:	GINA GOLIA
SIGNATURE:	/Gina Golia/
DATE SIGNED:	11/19/2014

Total Attachments: 12

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ASSIGNMENT

WHEREAS, WE,

1. **Eugene J. Baik**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of San Diego, California;
2. **Sameer Vermani**, a citizen of **India**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
3. **Lin Yang**, a citizen of **China P. R.**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
4. **Hemanth Sampath**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SYSTEMS AND METHODS FOR COMMUNICATION OVER A PLURALITY OF FREQUENCIES AND STREAMS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/690,481** filed **November 30th, 2012** Qualcomm Reference No. **120674U1** and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/566,583**, filed **December 2nd, 2011**, Qualcomm Reference No. **120674P1**, U.S. Provisional Application No(s). **61/569,455**, filed **December 12th, 2011**, Qualcomm Reference No. **120674P2**, U.S. Provisional Application No(s). **61/592,560**, filed **January 30th, 2012**, Qualcomm Reference No. **120674P3**, U.S. Provisional Application

No(s). **61/598,187**, filed **February 13th, 2012**, Qualcomm Reference No. **120674P4**, U.S. Provisional Application No(s). **61/621,880**, filed **April 9th, 2012**, Qualcomm Reference No. **120674P5**, U.S. Provisional Application No(s). **61/624,866**, filed **April 16th, 2012**, Qualcomm Reference No. **120674P6**, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

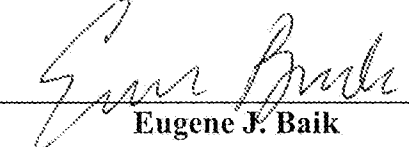
AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, California on 1/23/13 
LOCATION DATE Eugene J. Baik

Done at San Diego, California on _____
LOCATION DATE Sameer Vermani

Done at San Diego, California on _____
LOCATION DATE Lin Yang

Done at San Diego, California on _____
LOCATION DATE Hemanth Sampath

ASSIGNMENT

WHEREAS, WE,

1. **Eugene J. Baik**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of San Diego, California;
2. **Sameer Vermani**, a citizen of **India**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
3. **Lin Yang**, a citizen of **China P. R.**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
4. **Hemanth Sampath**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SYSTEMS AND METHODS FOR COMMUNICATION OVER A PLURALITY OF FREQUENCIES AND STREAMS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/690,481** filed **November 30th, 2012** Qualcomm Reference No. **120674U1** and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/566,583**, filed **December 2nd, 2011**, Qualcomm Reference No. **120674P1**, U.S. Provisional Application No(s). **61/569,455**, filed **December 12th, 2011**, Qualcomm Reference No. **120674P2**, U.S. Provisional Application No(s). **61/592,560**, filed **January 30th, 2012**, Qualcomm Reference No. **120674P3**, U.S. Provisional Application

No(s). **61/598,187**, filed **February 13th, 2012**, Qualcomm Reference No. **120674P4**, U.S. Provisional Application No(s). **61/621,880**, filed **April 9th, 2012**, Qualcomm Reference No. **120674P5**, U.S. Provisional Application No(s). **61/624,866**, filed **April 16th, 2012**, Qualcomm Reference No. **120674P6**, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, California on _____
LOCATION DATE

Eugene J. Baik

Done at San Diego, California on 03/04/2013
LOCATION DATE

Sameer Vermani

Done at San Diego, California on _____
LOCATION DATE

Lin Yang

Done at San Diego, California on _____
LOCATION DATE

Hemanth Sampath

ASSIGNMENT

WHEREAS, WE,

1. **Eugene J. Baik**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of San Diego, California;
2. **Sameer Vermani**, a citizen of **India**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
3. **Lin Yang**, a citizen of **China P. R.**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;
4. **Hemanth Sampath**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of **San Diego, California**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SYSTEMS AND METHODS FOR COMMUNICATION OVER A PLURALITY OF FREQUENCIES AND STREAMS** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **13/690,481** filed **November 30th, 2012** Qualcomm Reference No. **120674U1** and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/566,583**, filed **December 2nd, 2011**, Qualcomm Reference No. **120674P1**, U.S. Provisional Application No(s). **61/569,455**, filed **December 12th, 2011**, Qualcomm Reference No. **120674P2**, U.S. Provisional Application No(s). **61/592,560**, filed **January 30th, 2012**, Qualcomm Reference No. **120674P3**, U.S. Provisional Application

No(s). **61/598,187**, filed **February 13th, 2012**, Qualcomm Reference No. **120674P4**, U.S. Provisional Application No(s). **61/621,880**, filed **April 9th, 2012**, Qualcomm Reference No. **120674P5**, U.S. Provisional Application No(s). **61/624,866**, filed **April 16th, 2012**, Qualcomm Reference No. **120674P6**, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, California on _____
LOCATION DATE **Eugene J. Baik**

Done at San Diego, California on _____
LOCATION DATE **Sameer Vermani**

Done at San Diego, California on 1/23/2013
LOCATION DATE **Lin Yang**

Done at San Diego, California on _____
LOCATION DATE **Hemanth Sampath**

ASSIGNMENT

WHEREAS, WE,

1. **Eugene J. Baik**, a citizen of **the United States of America**, having a mailing address of 5775 Morehouse Drive, San Diego, California, 92121, US; and a resident of San Diego, California;
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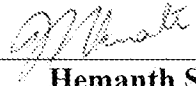
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Done at San Diego, California on _____
LOCATION DATE **Eugene J. Baik**

Done at San Diego, California on _____
LOCATION DATE **Sameer Vermani**

Done at San Diego, California on _____
LOCATION DATE **Lin Yang**

Done at San Diego, California on 04/09/13
LOCATION DATE 
Hemanth Sampath